

L Number	Hits	Search Text	DB	Time stamp
1	5	underbump adj metal adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:45
2	1	underbump adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
3	61861	barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
4	1080	metal adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
5	83324	bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:50
6	60	(metal adj barrier adj layer) and bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:10
7	165035	support adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
8	17775	second adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
9	410	(support adj member) and (second adj area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
10	1705364	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
11	80	((support adj member) and (second adj area)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12
12	10	((((support adj member) and (second adj area)) and substrate) and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12

The screenshot shows a web browser window with a search interface. At the top, there are buttons for "Search", "Browse", "Links", and "New". Below these, a search bar contains the text "USPAT: US-PGPUB:EPD:JPO:DERWENT:IBM\_TDS". To the right of the search bar, there are checkboxes for "Details" and "Highlight all full term validity". Below the search bar, the text "Default operator: DR" is visible. The main content area displays the search result "6175157" in a large, bold font. At the bottom of the browser window, there is a status bar with icons for "Back", "Forward", "Home", "Stop", "Print", "Text", and "HTML".

 B&B Form
  US & R Form
  IntelliForm
  Text
  HTML

[↗ HNS](#)
[🔍 Details](#)
[📄 HTML](#)

EAST - [thinsearch15.wsp:1]

File View Edit Tools Window Help

L29: (60) epoxy adj spacer  
L30: (2) epoxy adj dummy  
L31: (8) 29 and 14  
L32: (122) resin adj bump  
L33: (12) plastic adj bump  
L34: (37) epoxy adj bump  
L35: (30) 14 and 34  
L36: (18) dummy adj plastic  
L37: (631) resin adj spacer  
L38: (68) 14 and 37  
L39: (11) 38 and package  
L40: (1) 10 and 37  
L41: (6) "6208022"  
L42: (14744) flexible adj substrate  
L43: (7) 17 and 42  
L44: (68) support adj bump  
L45: (39) 44 and semiconductor  
L46: (60308) supporting adj member  
L47: (172) 46 and 42  
L48: (478) supporting adj spacer  
L49: (1) 48 and 42  
L50: (0) 48 and semiconductor and package  
L51: (25) 48 and semiconductor  
L52: (9) "5635756"  
L53: (11) "6175157"

DB: USPAT: US PGPUH: EPO: JPO: DERWENT: IBM: 108  
Data: operator OR  
"6175157"

Failed

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	NUM	Image 1
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6590286 B2	20030708	12	Land grid array semiconductor device	257/737	257/738; 257/780;		Okada, Makio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6590
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6583512 B2	20030624	27	Semiconductor device and method for fabricating the same	257/777	257/666; 257/675;		Nakaoka, Yukiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6583
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6537855 B2	20030325	7	Semiconductor device and method of manufacturing the same	438/118	257/E21.503; 257/E21.514;		Taguchi, Yutaka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6537
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6483190 B1	20021119	22	Semiconductor chip element	257/737	257/690;		Kainuma, Norio et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6483
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6462420 B2	20021008	9	Semiconductor chip and semiconductor device having a chip-	257/777	257/786;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6462
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6426559 B1	20020730	7	Miniature 3D multi-chip module	257/777	257/E23.021; 257/666;		Bryan, Robert Newell et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6426
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6424033 B1	20020723	12	Chip package with grease heat sink and method of making	257/718	257/E21.503; 257/E23.087;		Akram, Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6424
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6376914 B2	20020423	10	Dual-die integrated circuit package	257/777	257/666;		Kovats, Julius A. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6376
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6285084 B1	20010904	14	Semiconductor device	257/777	257/685; 257/80;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6285

EAST - [thinsearch15.wsp:1]

FileViewEditToolsWindowHelp

Active

DBs

USPAT:USFSPUB:EPJ:JPO:DERWENT:BM\_IDB

Default operation:OR

11 and bump

11 and bump

11 and bump

L1: (5) underbump adj metal adj layer

L2: (1) underbump adj barrier adj layer

L3: (61861) barrier adj layer

L4: (1080) metal adj barrier adj layer

L5: (83324) bump\$1

L6: (60) 4 and 5

L7: (165035) support adj member

L8: (17775) second adj area

L9: (410) 7 and 8

L10: (1705364) substrate

L11: (80) 9 and 10

L12: (10) 11 and bump

USPAT:USFSPUB:EPJ:JPO:DERWENT:BM\_IDB

Default operation:OR

11 and bump

11 and bump

11 and bump

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	2	3	Image Do
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030017654 A1	20030123	22	Semiconductor chip having a supporting member, tape substrate, s	438/127	257/E21.503; 257/E23.065;		Iwamoto, Naofumi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200300
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20020117330 A1	20020829	155	Resilient contact structures formed and then attached to a substrate	174/260	174/267; 257/E21.503;		Eldridge, Benjamin Niles et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200201
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20020047214 A1	20020425	18	Multi-chip package-type semiconductor device	257/778	257/E23.069; 257/E23.125;		Morinaga, Yuichi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200200
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20010020546 A1	20010913	155	Electrical contact structures formed by configuring a flexible wire to have	174/261	174/24; 174/255;		Eldridge, Benjamin N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200100
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20010020545 A1	20010913	155	Electrical contact structures formed by configuring a flexible wire to have	174/260	257/618; 257/E21.503;		Eldridge, Benjamin N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200100
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6683369 B2	20040127	20	Semiconductor chip having a supporting member, tape substrate, s	257/676	257/692		Iwamoto, Naofumi	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 668336
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6518655 B2	20030211	16	Multi-chip package-type semiconductor device	257/678	257/686; 257/E23.069;		Morinaga, Yuichi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 651865
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6110823 A	20000829	130	Method of modifying the thickness of a plating on a member by creating a te	438/660	257/E21.503; 257/E21.508;		Eldridge, Benjamin N. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 611082
9	<input type="checkbox"/>	<input type="checkbox"/>	US 4849857 A	19890718	11	Heat dissipating interconnect tape for use in tape automated bonding	361/708	257/668; 257/E23.034;		Butt, Sheldon H. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 484985
10	<input type="checkbox"/>	<input type="checkbox"/>	US 4827376 A	19890502	12	Heat dissipating interconnect tape for use in tape automated bonding	361/708	257/E23.034; 257/E23.055;		Voss, Scott V.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 482737

Ready

CAP NUM